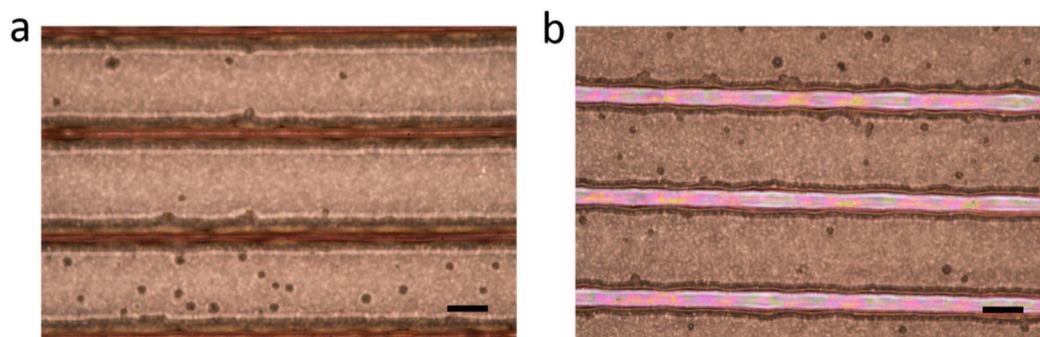
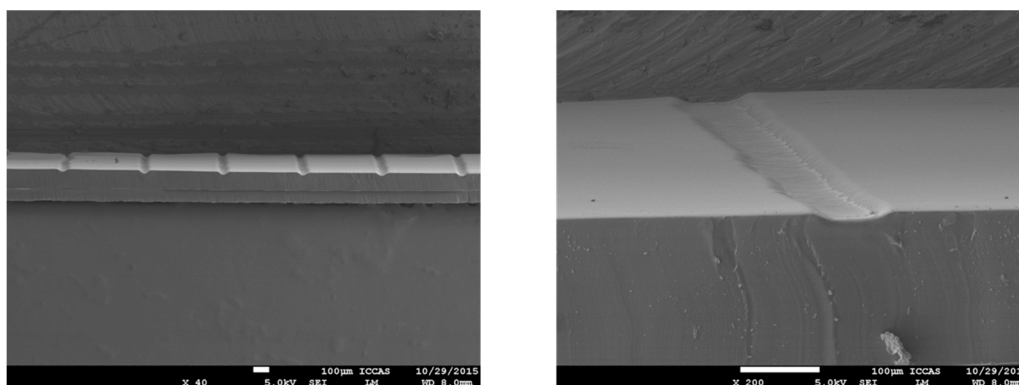


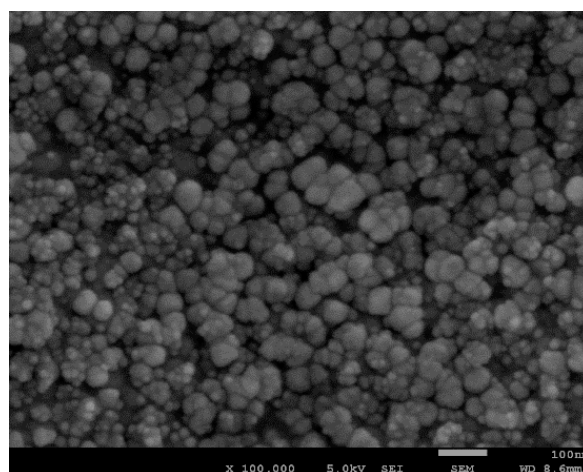
## Supplementary Materials: Fabrication of Bendable Circuits on a Polydimethylsiloxane (PDMS) Surface by Inkjet Printing Semi-Wrapped Structures



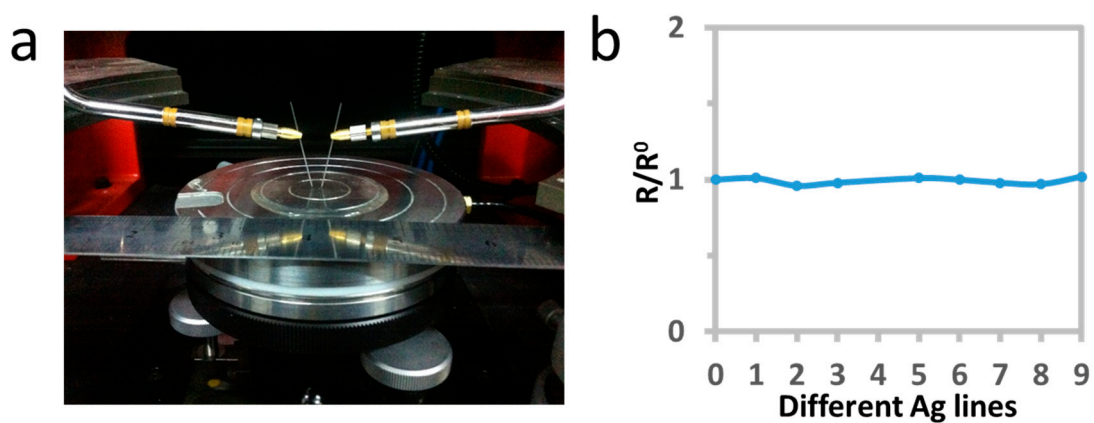
**Figure S1.** Optical images of printed deposits on the precured PDMS substrate with different focal planes. (a) The inkjet printed patterns on the precured PDMS substrate after heating for 0 min, at 80 °C; (b) The inkjet printed patterns on the precured PDMS substrate after heating for 10 min, at 80 °C. Scale bar: 100  $\mu$ m.



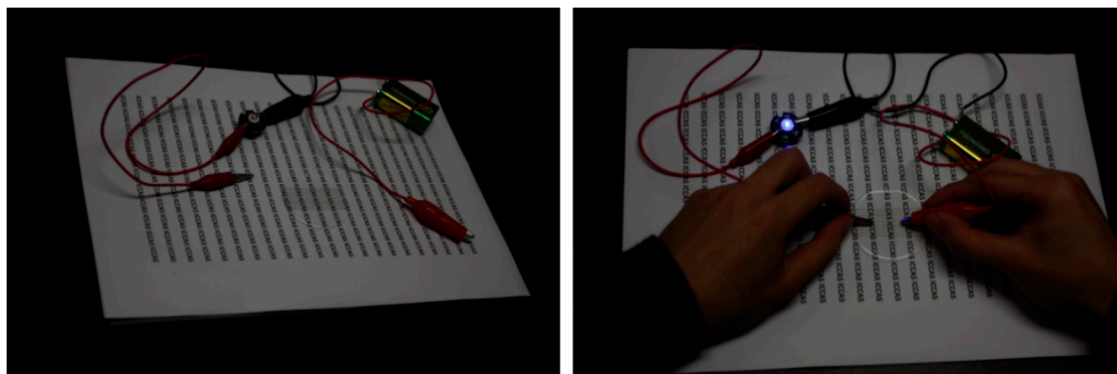
**Figure S2.** SEM images of printed deposits on the precured PDMS substrate with a low ink concentration (3 wt. %).



**Figure S3.** Magnified SEM image of the printed deposits after reduction, indicating that the particle size of the reduced AgNPs was about 50–100 nm.



**Figure S4.** The conductivity of the different Ag lines (a) Photograph of the equipment and process of electrical measurements of the fabricated circuits; (b) The resistance change of the different Ag lines with a certain length, with  $R$  and  $R^0$  indicating the resistance of one initial Ag line and the others, respectively.



**Figure S5.** Demonstration of the bendability of the fabricated circuits. After bending 800 times, an LED was still lit with the bent film as conductive unit.